

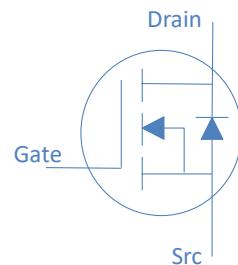
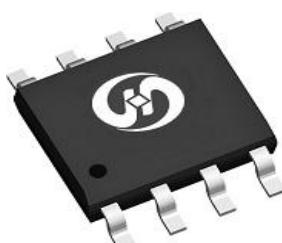
**60V N-Ch Power MOSFET**
**Feature**

- ◊ High Speed Power Switching, Logic Level
- ◊ Enhanced Body diode dv/dt capability
- ◊ Enhanced Avalanche Ruggedness
- ◊ 100% UIS Tested, 100% Rg Tested
- ◊ Lead Free, Halogen Free

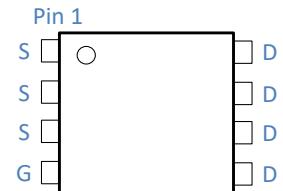
$V_{DS}$	60	V	
$R_{DS(on),typ}$	$V_{GS}=10V$	4.5	$m\Omega$
$R_{DS(on),typ}$	$V_{GS}=4.5V$	5.8	$m\Omega$
$I_D$	17	A	

**Application**

- ◊ Synchronous Rectification in SMPS
- ◊ Hard Switching and High Speed Circuit
- ◊ DC/DC in Telecoms and Industrial

**SOIC-8**


Part Number	Package	Marking
HGS060N06SL	SOIC-8	GS060N06SL


**Absolute Maximum Ratings at  $T_j=25^\circ C$  (unless otherwise specified)**

Parameter	Symbol	Conditions	Value	Unit
Continuous Drain Current	$I_D$	$T_C=25^\circ C$	17	A
		$T_C=100^\circ C$	11	
Drain to Source Voltage	$V_{DS}$	-	60	V
Gate to Source Voltage	$V_{GS}$	-	$\pm 20$	V
Pulsed Drain Current	$I_{DM}$	-	90	A
Avalanche Energy, Single Pulse	$E_{AS}$	$L=0.4mH, T_C=25^\circ C$	80	mJ
Power Dissipation	$P_D$	$T_C=25^\circ C$	3.1	W
Operating and Storage Temperature	$T_J, T_{stg}$	-	-55 to 150	°C

**Absolute Maximum Ratings**

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-Lead	$R_{\theta JL}$	23	°C/W
Thermal Resistance Junction-Ambient ( $t \leq 10s$ )	$R_{\theta JA}$	40	°C/W
Thermal Resistance Junction-Ambient (steady state)		75	°C/W

**Electrical Characteristics at  $T_j=25^\circ\text{C}$  (unless otherwise specified)**
**Static Characteristics**

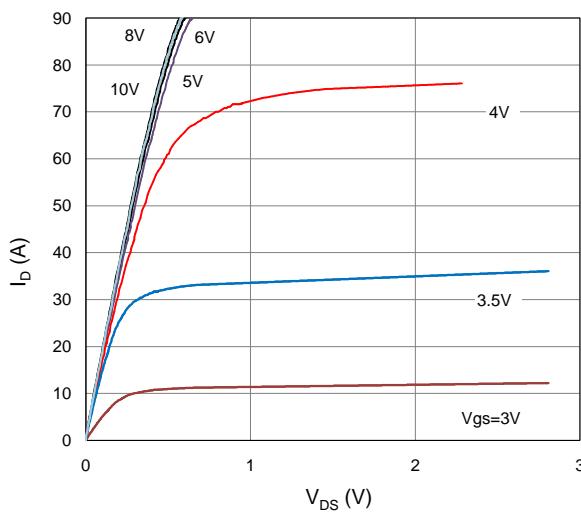
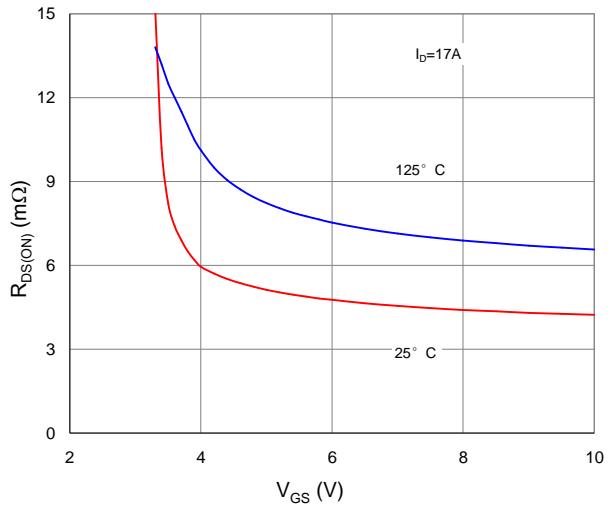
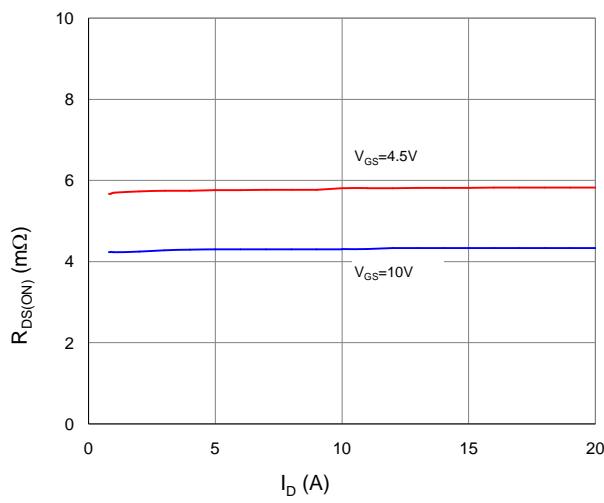
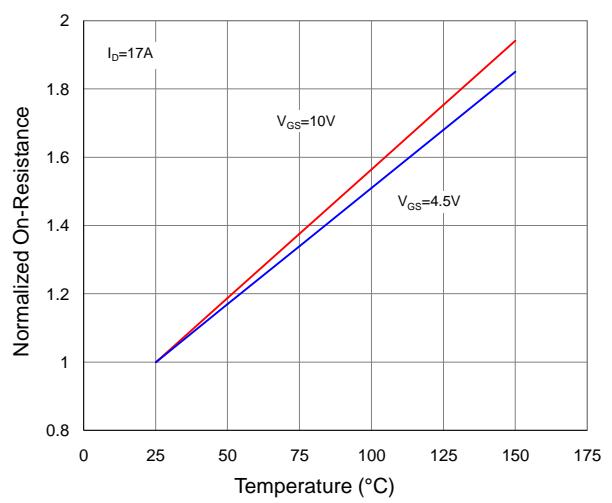
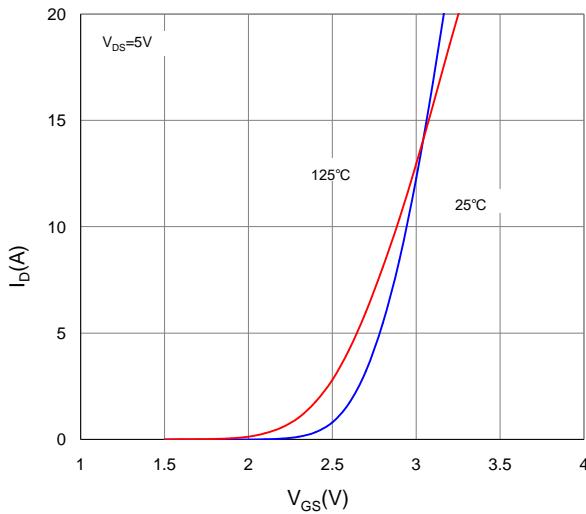
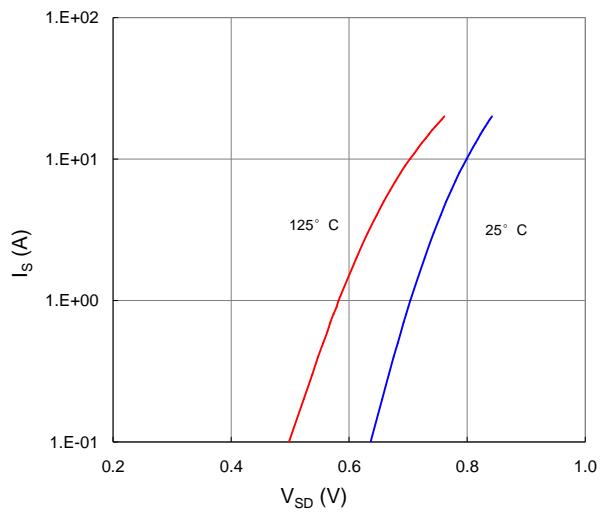
Parameter	Symbol	Conditions	Value			Unit
			min	typ	max	
Drain to Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$	60	-	-	V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_D=250\mu\text{A}$	1.0	1.6	2.4	
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=60\text{V}, T_j=25^\circ\text{C}$	-	-	1	$\mu\text{A}$
		$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=60\text{V}, T_j=100^\circ\text{C}$	-	-	100	
Gate to Source Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	nA
Drain to Source on Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10\text{V}, I_D=17\text{A}$	-	4.5	6	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_D=15\text{A}$	-	5.8	8	
Transconductance	$g_{\text{fs}}$	$V_{\text{DS}}=5\text{V}, I_D=17\text{A}$	-	45	-	S
Gate Resistance	$R_G$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}} \text{ Open}, f=1\text{MHz}$	-	1.5	-	$\Omega$

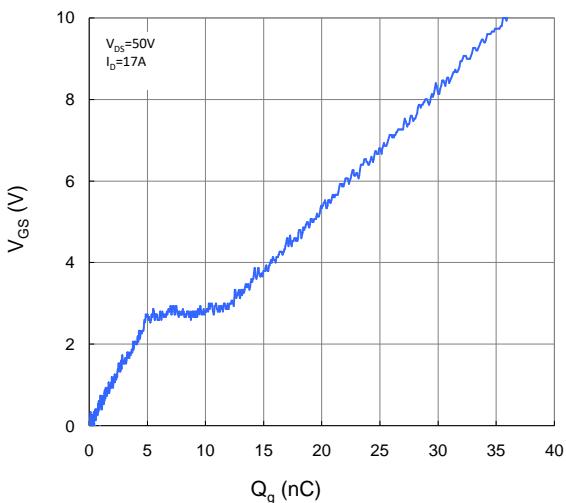
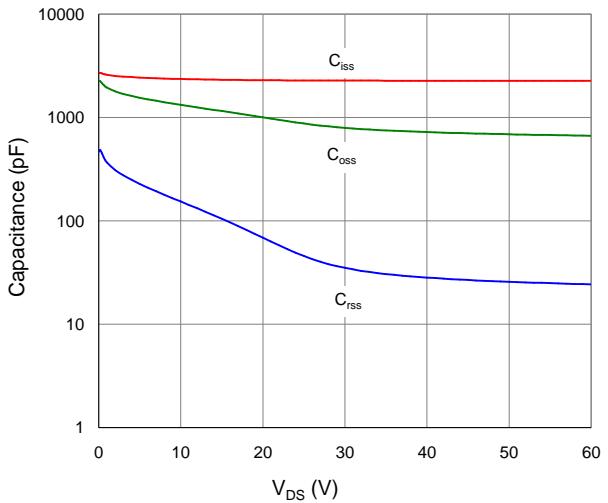
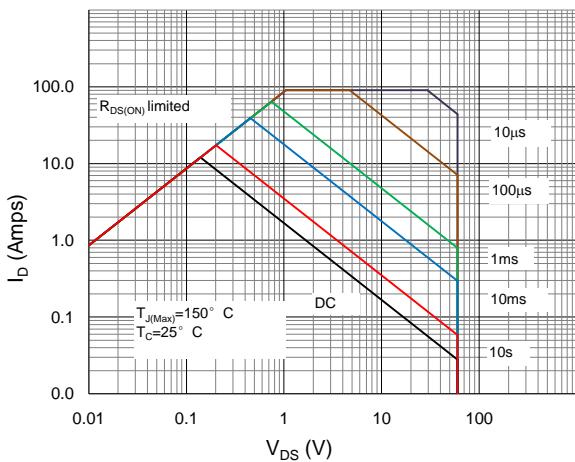
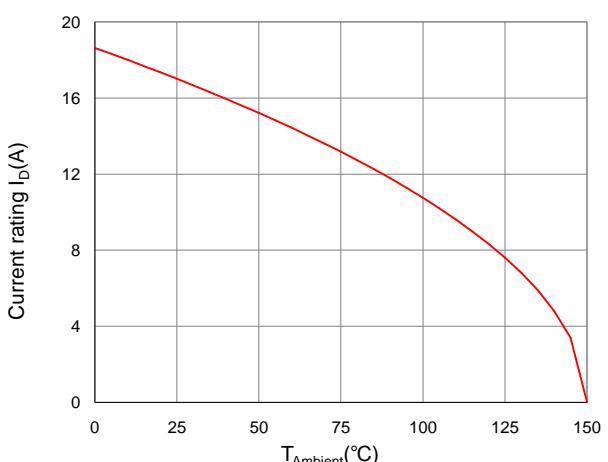
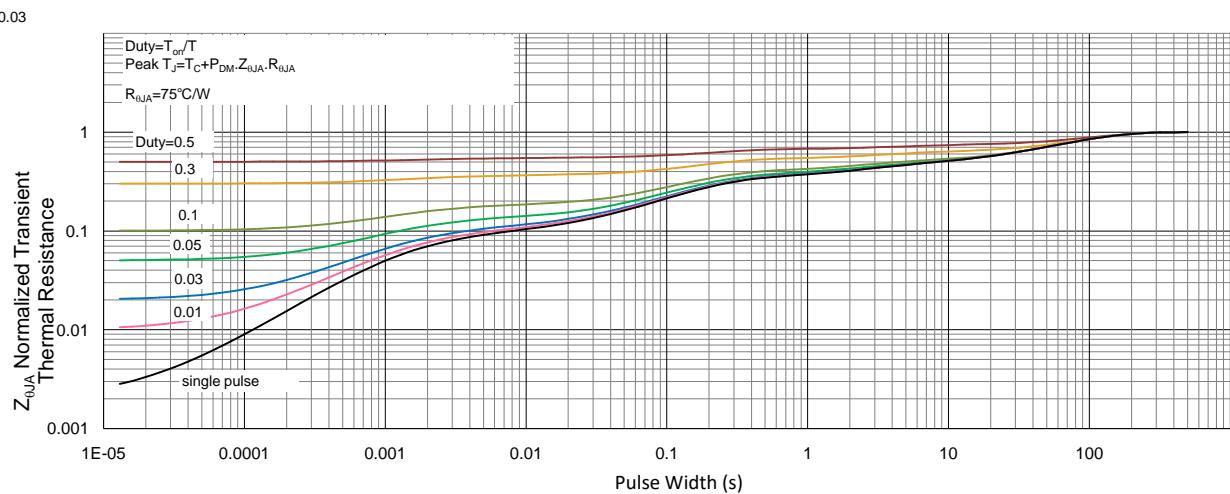
**Dynamic Characteristics**

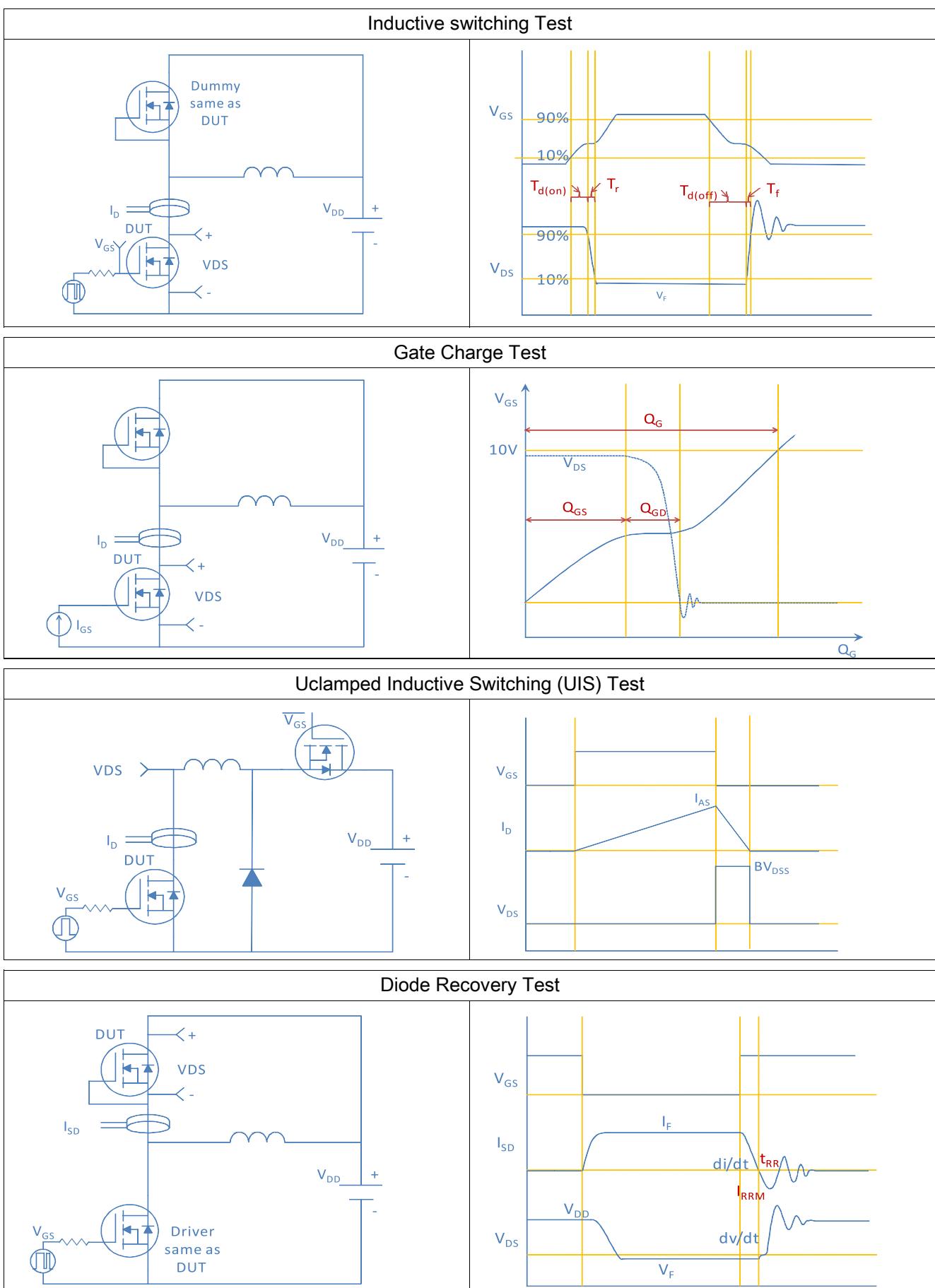
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=30\text{V}, f=1\text{MHz}$	-	2274	-	pF
Output Capacitance	$C_{\text{oss}}$		-	793	-	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	35	-	
Total Gate Charge	$Q_g(10\text{V})$	$V_{\text{DD}}=30\text{V}, I_D=17\text{A}, V_{\text{GS}}=10\text{V}$	-	36	-	nC
Total Gate Charge	$Q_g(4.5\text{V})$		-	18	-	
Gate to Source Charge	$Q_{\text{gs}}$		-	5	-	
Gate to Drain (Miller) Charge	$Q_{\text{gd}}$		-	8	-	
Turn on Delay Time	$t_{\text{d}(\text{on})}$		-	11	-	
Rise time	$t_r$	$V_{\text{DD}}=30\text{V}, I_D=17\text{A}, V_{\text{GS}}=10\text{V}, R_G=10\Omega,$	-	7	-	ns
Turn off Delay Time	$t_{\text{d}(\text{off})}$		-	35	-	
Fall Time	$t_f$		-	10	-	

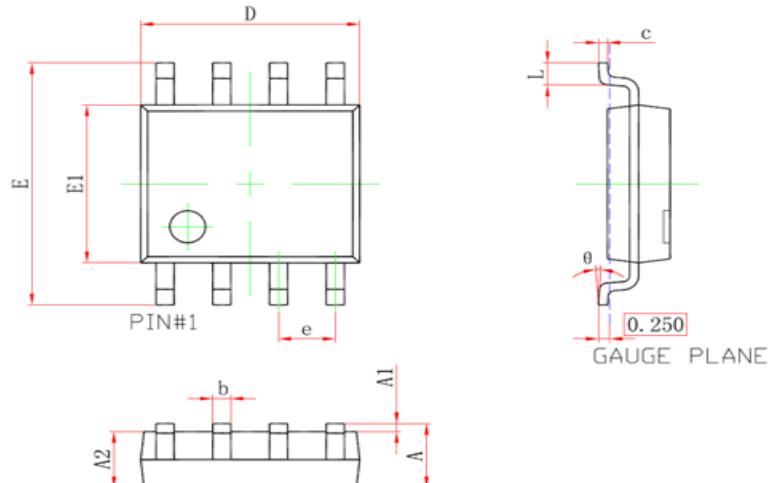
**Reverse Diode Characteristics**

Diode Forward Voltage	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_F=17\text{A}$	-	0.9	1.2	V
Reverse Recovery Time	$t_{\text{rr}}$	$V_R=30\text{V}, I_F=17\text{A}, dI_F/dt=300\text{A}/\mu\text{s}$	-	30	-	ns
Reverse Recovery Charge	$Q_{\text{rr}}$		-	53	-	nC

**Fig 1. Typical Output Characteristics**

**Figure 2. On-Resistance vs. Gate-Source Voltage**

**Figure 3. On-Resistance vs. Drain Current and Gate Voltage**

**Figure 4. Normalized On-Resistance vs. Junction Temperature**

**Figure 5. Typical Transfer Characteristics**

**Figure 6. Typical Source-Drain Diode Forward Voltage**


**Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage**

**Figure 8. Typical Capacitance vs. Drain-to-Source Voltage**

**Figure 9. Maximum Safe Operating Area**

**Figure 10. Maximum Drain Current vs. Case Temperature**

**Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Ambient**




**Package Outline**
**SOIC-8, 8 leads**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.250	1.650	0.049	0.065
b	0.310	0.510	0.012	0.020
c	0.170	0.250	0.007	0.010
D	4.800	5.000	0.189	0.197
e	1.270 (BSC)		0.050 (SBC)	
E	5.800	6.200	0.228	0.244
E1	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.031
θ	0°	8°	0°	8°